

# 18V, 4A Synchronous Step-Down DC/DC Converter

### **Description**

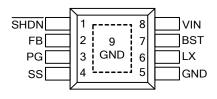
The FR9854 is a synchronous step-down DC/DC converter with fast constant on time control technique (FCOT) that provides 4.5V to 18V input voltage range and 4A continuous load current capability. At light load condition, the FR9854 can operate at power saving mode to support high efficiency and reduce power loss.

The FR9854 fault protection includes cycle-by-cycle current limit, UVLO, short circuit protection and thermal shutdown. The soft-start function prevents inrush current at turn-on. The characteristics scheme of FR9854 are fast constant on time control which provides fast transient response, the noise immunity and all kinds of very low ESR output capacitor for ensuring performance stabilization.

The FR9854 is offered in SOP-8L (Exposed Pad) and TQFN-16L (3mmx3mm) packages, which provides good thermal conductance.

### Pin Assignments

SP Package: SOP-8L (Exposed Pad)



W3 Package: TQFN-16L (3mmx3mm)

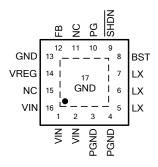


Figure 1. Pin Assignments of FR9854

#### **Features**

- Low R<sub>DS(ON)</sub> Integrated Power MOSFET (75mΩ/50mΩ)
- FCOT Mode Enables Fast Transient Response
- Wide Input Voltage Range: 4.5V to 18V
- 0.765V Reference Voltage (for FR9854SP Only)
- 0.8V Reference Voltage for (for FR9854W3 Only)
- 8V Maximum Output Voltage
- 4A Output Current
- 630kHz Pseudo Frequency
- Power Good Function
- Adjustable Soft-Start Function (for FR9854SP Only)
- Internal 1ms Soft-Start (for FR9854W3 Only)
- Cycle-by-Cycle Current Limit
- Over Temperature Protection with Auto Recovery
- Input Under Voltage Lockout
- Hiccup Short Circuit Protection
- SOP-8L (Exposed Pad) and TQFN-16L (3mmx3mm) Packages

### **Applications**

- STB (Set-Top-Box)
- LCD Display, TV
- Distributed Power System
- Networking, XDSL Modem

### **Ordering Information**

FR9854
Package Type
SP: SOP-8L (Exposed Pad)
W3: TQFN-16L (3mmx3mm)



### **Typical Application Circuit**

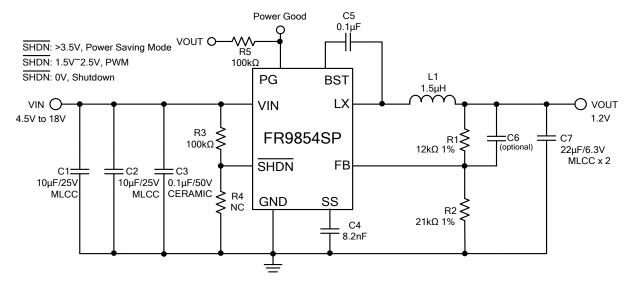


Figure 2. Application Circuit for SOP-8L (Exposed Pad) Package

V<sub>IN</sub>=12V, the recommended BOM list is as below.

	( 121) the recommended 2011 here to be below							
<b>V</b> out	C1	R1	R2	C2	C6	L1	C7	
1.05V	10µF MLCC	7.87kΩ	21kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2	
1.2V	10µF MLCC	12kΩ	21kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2	
1.8V	10µF MLCC	28kΩ	21kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2	
3.3V	10µF MLCC	69.8kΩ	21kΩ	10µF MLCC	5pF~33pF	2.2µH	22µF MLCC x2	
5V	10µF MLCC	118kΩ	21kΩ	10µF MLCC	5pF~33pF	3.3µH	22µF MLCC x2	

Table 1. Recommended Component Values



### **Typical Application Circuit (Continued)**

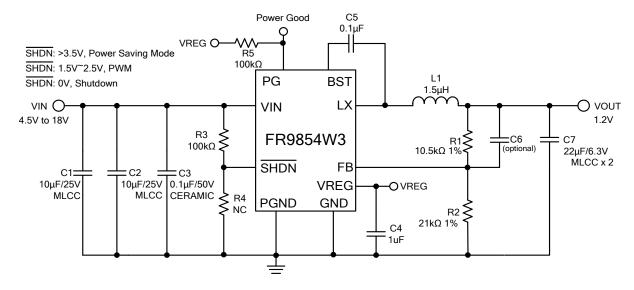


Figure 3. Application Circuit for TQFN-16L (3mmx3mm) Package

V<sub>IN</sub>=12V, the recommended BOM list is as below.

V <sub>OUT</sub>	C1	R1	R2	C2	C6	L1	C7
1.05V	10µF MLCC	6.49kΩ	20.5kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2
1.2V	10µF MLCC	10.5kΩ	21kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2
1.8V	10µF MLCC	26.7kΩ	21kΩ	10µF MLCC	5pF~33pF	1.5µH	22µF MLCC x2
3.3V	10µF MLCC	71.5kΩ	22.6kΩ	10µF MLCC	5pF~33pF	2.2µH	22µF MLCC x2
5V	10µF MLCC	110kΩ	21kΩ	10µF MLCC	5pF~33pF	3.3µH	22µF MLCC x2

Table 2. Recommended Component Values



### **Functional Pin Description**

Pin Name	Pin No. SOP-8L(EP)	Pin No. TQFN-16L(3x3)	Pin Function
SHDN	1	9	This pin includes enable the converter on/off, and select operation mode (The mode setting, please refer to the following page 10). Connect VIN with a $100k\Omega$ resistor for self-startup and operate in power saving mode.
FB	2	12	Voltage feedback input pin. Connect FB and VOUT with a resistive voltage divider. This IC senses feedback voltage via FB and regulates voltage of FR9854SP is 0.765V and FR9854W3 is 0.8V.
PG	3	10	Open drain power good output.
SS	4	х	Soft-start pin. This pin controls the soft-start period. Connect a capacitor from SS to GND to set the soft-start period.
GND	5	13	Ground pin.
LX	6	5,6,7	Power switching node. Connect an external inductor to this switching node.
BST	7	8	High side gate drive boost pin. A capacitor rating between 0.1uF~1uF must be connected from this pin to LX. It can boost the gate drive to fully turn on the internal high side NMOS.
VIN	8	1,2,16	Power supply input pin. Placed input capacitors as close as possible from VIN to GND to avoid noise influence.
Exposed Pad	9	17	Ground pin. The exposed pad must be soldered to a large PCB area and connected to GND for maximum power dissipation.
PGND	x	3,4	Power ground pin.
VREG	х	14	Regulator output. Connect a 1uF capacitor to GND to stabilize the internal regulator voltage.

### **Block Diagram**

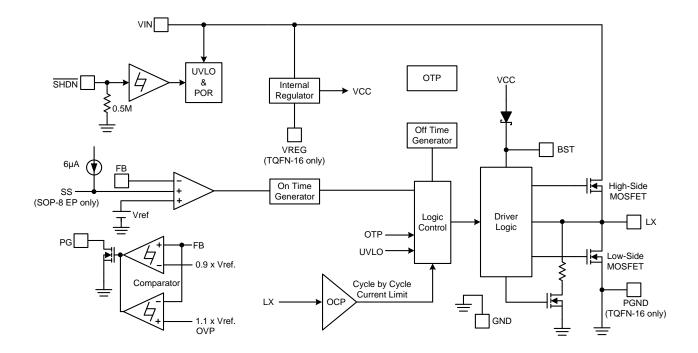


Figure 4. Block Diagram of FR9854



## Absolute Maximum Ratings (Note 1)

Supply Voltage V <sub>IN</sub>	0.3V to +20V
• Enable Voltage V <sub>SHDN</sub>	0.3V to +20V
• LX Voltage V <sub>LX</sub>	0.3V to V <sub>IN</sub> +0.3V
Dynamic LX Voltage in 15ns Duration	5V to V <sub>IN</sub> +5V
BST Pin Voltage V <sub>BST</sub>	0.3V to V <sub>LX</sub> +6.5V
All Other Pins Voltage	0.3V to +6V
Maximum Junction Temperature (T <sub>J</sub> )	- +150°C
• Storage Temperature (Ts)	65°C to +150°C
• Lead Temperature (Soldering, 10sec.)	- +260°C
<ul> <li>Package Thermal Resistance, (θ<sub>JA</sub>) (Note 2)</li> </ul>	
SOP-8L (Exposed Pad)	- 60°C/W
TQFN-16L (3mmx3mm)	- 62°C/W
<ul> <li>Package Thermal Resistance, (θ<sub>JC</sub>) (Note 2)</li> </ul>	
SOP-8L (Exposed Pad)	- 15°C/W
TQFN-16L (3mmx3mm)	- 46°C/W

Note 1: Stresses beyond this listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Note 2:  $\theta_{JA}$  is measured at TA=25°C on a high effective thermal conductivity 4-layer test PCB of JEDEC-51-7.  $\theta_{JC}$  is measured at the exposed pad. The thermal resistance greatly varies with layout, copper thickness, number of layers and PCB size.

### **Recommended Operating Conditions**

Supply Voltage V <sub>IN</sub>	- +4.5V to +18V
Operating Ambient Temperature Range	40°C to +85°C
Operating Junction Temperature Range	40°C to +125°C



### **Electrical Characteristics**

(V<sub>IN</sub>=12V, T<sub>A</sub>=25°C, unless otherwise specified.)

Parameter	Symbol	Condit	ions	Min	Тур	Max	Unit
V <sub>IN</sub> Quiescent Current	IDDQ	V <sub>SHDN</sub> =5V, V <sub>FB</sub> =1V			0.6	1	mA
V <sub>IN</sub> Shutdown Supply Current	I <sub>SD</sub>	V <sub>SHDN</sub> =0V			1	10	μA
Feedback Voltage	V <sub>FB</sub>		FR9854SP FR9854W3	0.75 0.788	0.765 0.8	0.78 0.812	V
Feedback Input Current	I <sub>FB</sub>	V <sub>FB</sub> =1V			0.01	0.1	μΑ
High-Side MOSFET R <sub>DS(ON)</sub>	R <sub>DS(ON)</sub>				75		mΩ
Low-Side MOSFET R <sub>DS(ON)</sub>	R <sub>DS(ON)</sub>				50		mΩ
Current Limit (Note 3)	ILIMIT				5.5		Α
Low Side Current Limit (Note 3)	ILOW_LIMIT	PWM mode			1.5		Α
On Time (Note 3)	Ton	V <sub>IN</sub> =12V, V <sub>OUT</sub> =1.0	5V		155		ns
Minimum Off Time	T <sub>OFF(MIN)</sub>	V <sub>FB</sub> =0.6V			250		ns
Input Supply Voltage UVLO Threshold	VUVLO(Vth)	V <sub>IN</sub> Rising			4.1		V
UVLO Threshold Hysteresis	Vuvlo(HYS)				0.35		V
Soft Start Charge Current	Iss	V <sub>SS</sub> =0V			6		μΑ
Internal Soft-Start Period	Tss	FR9854W3			1		ms
SHDN Input Low Voltage	V <sub>SHDN(L)</sub>					0.5	V
SHDN Input High Voltage	V <sub>SHDN(H)</sub>			1.5			V
Output Discharge Resistance	Rdischg				100		Ω
REG Output Voltage	V <sub>REG</sub>	6V≦V <sub>IN</sub> ≦18V, FR98	854W3		4.1		V
REG Output Current	I <sub>REG</sub>	V <sub>REG</sub> =4.1V, FR985	4W3		10		mA
Under Voltage Detect Threshold	Vuv			0.36	0.4	0.44	٧
Power Good Threshold (Note 3)	$V_{PG}$	V <sub>FB</sub> Rising V <sub>FB</sub> Falling		85	90 85	95	%
Power Good Sink Current	I <sub>PG</sub>	V <sub>PG</sub> =0.5V			5		mA
Thermal Shutdown Threshold (Note 3)	T <sub>SD</sub>				160		°C
Thermal Shutdown Hysteresis (Note 3)	T <sub>HYS</sub>				30		°C

Note 3: Not production tested.



### **Typical Performance Curves**

 $V_{\text{IN}} = 12 \text{V}, \ V_{\text{OUT}} = 1.2 \text{V}, \ C1 = 10 \mu \text{Fx2}, \ C7 = 22 \mu \text{Fx2}, \ L1 = 1.5 \mu \text{H}, \ T_{\text{A}} = +25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 

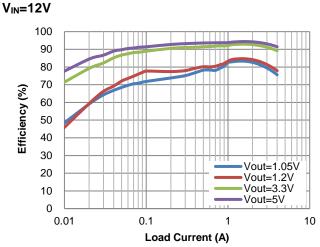


Figure 5. Efficiency vs. Load Current (FR9854SP)

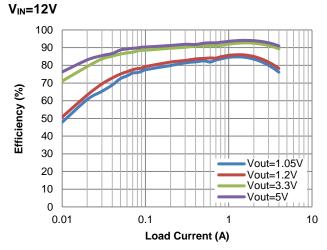


Figure 6. Efficiency vs. Load Current (FR9854W3)

# V<sub>IN</sub>=12V, V<sub>SHDN</sub>=2V

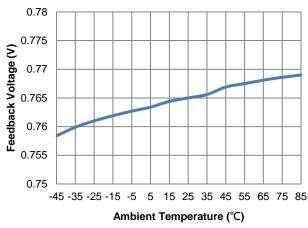


Figure 7. Feedback Voltage vs. Ambient Temperature (FR9854SP)

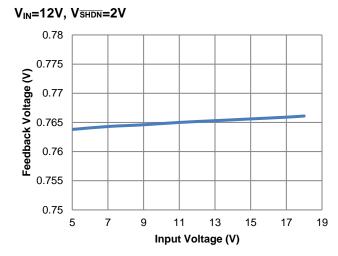


Figure 8. Feedback Voltage vs. Input Voltage (FR9854SP)



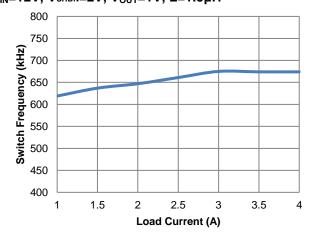


Figure 9. Switch Frequency vs. Load Current (FR9854SP)

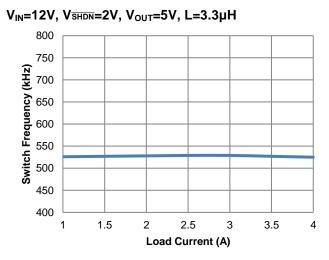


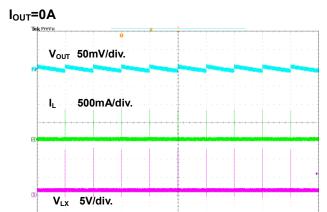
Figure 10. Switch Frequency vs. Load Current (FR9854SP)

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### **Typical Performance Curves (Continued)**

 $V_{\text{IN}}$ =12V,  $V_{\text{OUT}}$ =1.2V, C1=10 $\mu$ Fx2, C7=22 $\mu$ Fx2, L1=1.5 $\mu$ H,  $T_{\text{A}}$ =+25°C, unless otherwise noted. This is measured by using FR9854SP.



I<sub>OUT</sub>=4A

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V<sub>OUT</sub> 50mV/div.

I<sub>L</sub> 5A/div.

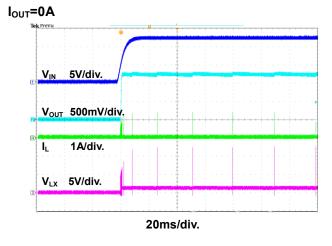
V<sub>LX</sub> 5V/div.

2µs/div.

Figure 11. Steady State Waveform

10ms/div.

Figure 12. Steady State Waveform



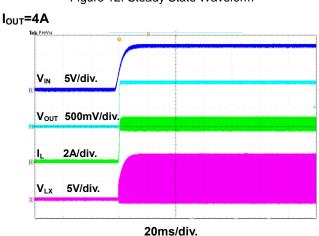
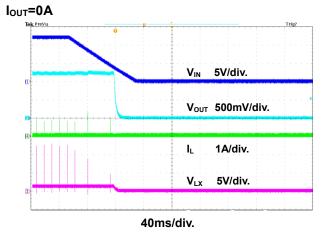


Figure 13. Startup Through Power Supply Waveform

Figure 14. Startup Through Power Supply Waveform



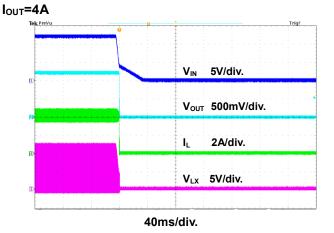


Figure 15. Shutdown Through Power Supply Waveform

Figure 16. Shutdown Through Power Supply Waveform



### **Typical Performance Curves (Continued)**

 $V_{\text{IN}}$ =12V,  $V_{\text{OUT}}$ =1.2V, C1=10 $\mu$ Fx2, C7=22 $\mu$ Fx2, L1=1.5 $\mu$ H,  $T_{\text{A}}$ =+25°C, unless otherwise noted. This is measured by using FR9854SP.

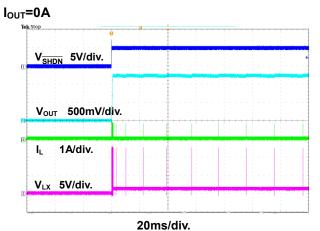


Figure 17. Startup Through SHDN Waveform

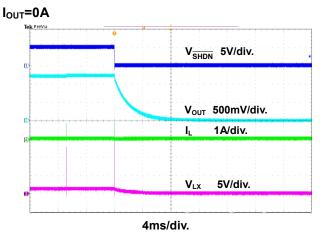


Figure 19. Shutdown Through SHDN Waveform

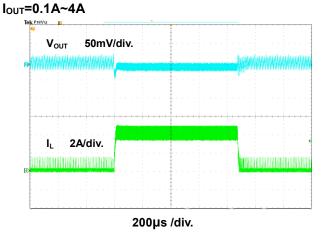


Figure 21. Load Transient Waveform

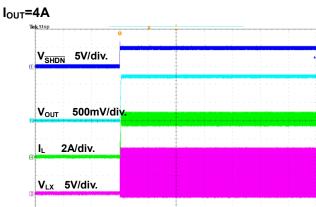


Figure 18. Startup Through SHDN Waveform

20ms/div.

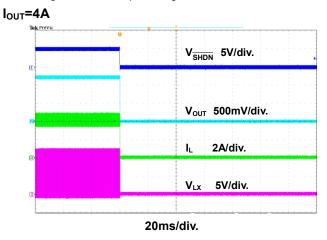


Figure 20. Shutdown Through SHDN Waveform



### **Function Description**

The FR9854 is a high efficiency and fast constant on time control mode step-down synchronous DC/DC converter. It has integrated high-side ( $75m\Omega$ , typ.) and low-side ( $50m\Omega$ , typ.) power switches, and provides 4A continuous load current. It regulates input voltage from 4.5V to 18V, and maximum output voltage to 8V. Using FCOT control scheme provides fast transient response, which can minimize the component size without additional external compensation network.

#### Enable / Mode

The FR9854 SHDN pin includes enable and mode function. Enable function provides digital control to turn on/off the converter. When the voltage of SHDN exceeds the threshold voltage, the converter starts the soft start function. If the SHDN pin voltage is below than the shutdown threshold voltage, the converter will turn into the shutdown mode and the shutdown current will be smaller than 1µA. The mode function can be selected in PWM or power saving mode. The mode setting can refer to following table.

SHDN	Mode
>3.5V	Power Saving Mode
1.5V~2.5V	PWM
0V	Shutdown

For auto start-up operation, connect  $\overline{SHDN}$  to VIN through a 100k $\Omega$  resistor, and the converter can automatically enter power saving mode.

#### Soft Start

The FR9854 employs adjustable soft start function to reduce input inrush current during start up. When the device turns on, a 6µA current begins charging the capacitor which is connected from SS pin to GND. The equation for the soft start time is shown as below:

$$T_{SS}(ms) = \frac{C_{SS}(nF) \times V_{FB}}{I_{SS}(\mu A)}$$

If a capacitor with 8.2nF is connected from SS pin to GND, the soft-start time will be about 1ms.

#### **Input Under Voltage Lockout**

When the FR9854 is power on, the internal circuits are held inactive until  $V_{\text{IN}}$  voltage exceeds the input UVLO threshold voltage. And the regulator will be disabled when  $V_{\text{IN}}$  is below the input UVLO threshold voltage. The hysteretic of the UVLO comparator is 350mV (typ.).



### **Function Description (Continued)**

#### **Over Current Protection**

The FR9854 over current protection function is implemented using cycle-by-cycle current limit architecture. The inductor current is monitored by Low-side MOSFET. When the load current increases, the inductor current also increases. When the valley inductor current reaches the current limit threshold, the output voltage starts to drop. When the over current condition is removed, the output voltage returns to the regulated value.

#### **Short Circuit Protection**

The FR9854 provides short circuit protection function to prevent the device damage from short condition. When the short condition occurs and the feedback voltage drops below 0.4V, the oscillator frequency will be reduce naturally and hiccup mode will be triggered to prevent the inductor current increasing beyond the current limit. Once the short condition is removed, the frequency will return to normal.

#### **Low Side Current Limit**

In PWM mode, the low side MOSFET will be turned on and the inductor current will inversely flow from output node to LX node when feedback voltage is larger than the reference voltage in certain situation. However, this inverse inductor current will destroy the low side MOSFET if this current is enough large. In order to avoid this problem, FR9854 would clamp this inverse current with 1.5A (typ.) until this situation is removed.

#### **Over Temperature Protection**

The FR9854 incorporates an over temperature protection circuit to protect itself from overheating. When the junction temperature exceeds the thermal shutdown threshold temperature, the regulator will be shutdown. And the hysteretic of the over temperature protection is 30°C (typ).

#### Power Good Signal Output (PG)

PG pin is an open-drain output and requires a pull up resistor. PG is actively held low in soft-start, standby, OVP and shutdown. It is released when the output voltage rises above 90% of nominal regulation point.

#### **Output Over Voltage Protection**

When the FB pin voltage exceeds 110%\*V<sub>ref</sub>, the output over voltage protection function will be triggered. The high-side/low-side MOSFET turn off and PG signal pull low.



### **Application Information**

#### **Output Voltage Setting**

The output voltage  $V_{\text{OUT}}$  is set using a resistive divider from the output to FB. The reference voltage of FR9854SP is 0.765V and FR9854W3 is 0.8V. Thus the output voltage equation is:

$$V_{OUT}$$
=0.765V× $\left(1+\frac{R1}{R2}\right)$  $\rightarrow$ FR9854SP

$$V_{OUT}=0.8V \times \left(1+\frac{R1}{R2}\right) \rightarrow FR9854W3$$

Place resistors R1 and R2 close to FB pin to prevent stray pickup.

#### **Input Capacitor Selection**

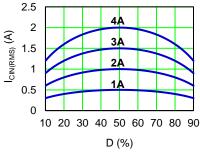
The use of the input capacitor is filtering the input voltage ripple and the MOSFETS switching spike voltage. Because the input current to the step-down converter is discontinuous, the input capacitor is required to supply the current to the converter to keep the DC input voltage. The capacitor voltage rating should be 1.25 to 1.5 times greater than the maximum input voltage. The input capacitor ripple current RMS value is calculated as:

$$I_{CIN(RMS)} = I_{OUT} \times \sqrt{D \times (1-D)}$$

$$D = \frac{V_{OUT}}{V_{IN}}$$

Where D is the duty cycle of the power MOSFET.

This function reaches the maximum value at D=0.5 and the equivalent RMS current is equal to  $I_{\text{OUT}}/2$ . The following diagram is the graphical representation of above equation.



A low ESR capacitor is required to keep the noise minimum. Ceramic capacitors are better, but tantalum or low ESR electrolytic capacitors may also suffice. When using tantalum or electrolytic capacitors, a  $0.1\mu F$  ceramic capacitor should be placed as close to the IC as possible.

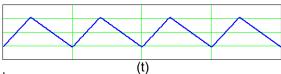
#### **Output Capacitor Selection**

The output capacitor is used to keep the DC output voltage and supply the load transient current. When operating in constant current mode, the output ripple is determined by four components:

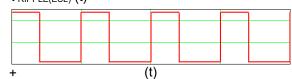
$$V_{RIPPLE}(t) = V_{RIPPLE(C)}(t) + V_{RIPPLE(ESR)}(t) + V_{RIPPLE(ESL)}(t) + V_{NOISE}(t)$$

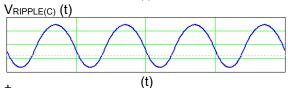
The following figures show the form of the ripple contributions.

#### VRIPPLE(ESR)(t)



#### V<sub>RIPPLE(ESL)</sub> (t)

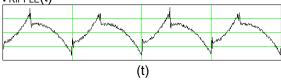








### V<sub>RIPPLE</sub>(t)





### **Application Information (Continued)**

$$V_{RIPPLE(ESR)} = \frac{V_{OUT}}{F_{OSC} \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times ESR$$

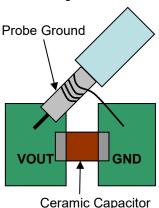
$$V_{RIPPLE(ESL)} = \frac{ESL}{I} \times V_{IN}$$

$$V_{RIPPLE(C)} = \frac{V_{OUT}}{8 \times F_{OSC^2} \times L \times C_{OUT}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

Where  $F_{\text{OSC}}$  is the switching frequency, L is the inductance value,  $V_{\text{IN}}$  is the input voltage, ESR is the equivalent series resistance value of the output capacitor, ESL is the equivalent series inductance value of the output capacitor and the  $C_{\text{OUT}}$  is the output capacitor.

Low ESR capacitors are preferred to use. Ceramic, tantalum or low ESR electrolytic capacitors can be used depending on the output ripple requirement. When using the ceramic capacitors, the ESL component is usually negligible.

It is important to use the proper method to eliminate high frequency noise when measuring the output ripple. The figure shows how to locate the probe across the capacitor when measuring output ripple. Removing the scope probe plastic jacket in order to expose the ground at the tip of the probe. It gives a very short connection from the probe ground to the capacitor and eliminating noise.



#### **Inductor Selection**

The output inductor is used for storing energy and filtering output ripple current. But the trade-off condition often happens between maximum energy storage and the physical size of the inductor. The first consideration for selecting the output inductor is to make sure that the inductance is large enough to keep the converter in the continuous current mode.

That will lower ripple current and result in lower output ripple voltage. The  $\Delta I_L$  is inductor peak-to-peak ripple current:

$$\Delta I_L = \frac{V_{OUT}}{F_{OSC} \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

A good compromise value between size and efficiency is to set the peak-to-peak inductor ripple current  $\Delta I_{\perp}$  equal to 30% of the maximum load current. But setting the peak-to-peak inductor ripple current  $\Delta I_{\perp}$  between 20%~50% of the maximum load current is also acceptable. Then the inductance can be calculated with the following equation:

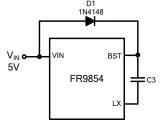
$$\Delta I_L = 0.3 \times I_{OUT(MAX)}$$

$$L = \frac{(V_{IN} - V_{OUT}) \times V_{OUT}}{V_{IN} \times F_{OSC} \times \Delta I_{L}}$$

The inductor saturation current should be selected larger than the current limit of FR9854.

#### **External Diode Selection**

For 5V input applications, it is recommended to add an external boost diode. This helps improving the efficiency. The boost diode can be a low cost one such as 1N4148.



#### **REG Capacitor Selection**

Connect a 1uF ceramic capacitor between the REG and GND, This helps stabilize the internal regulator voltage.



### **Application Information (Continued)**

#### **PCB Layout Recommendation**

The device's performance and stability is dramatically affected by PCB layout. It is recommended to follow these general guidelines shown as below:

- Place the input capacitors and output capacitors as close to the device as possible. Trace to these capacitors should be as short and wide as possible to minimize parasitic inductance and resistance.
- 2. Place feedback resistors close to the FB pin.
- 3. Keep the sensitive signal (FB) away from the switching signal (LX).
- 4. The exposed pad of the package should be soldered to an equivalent area of metal on the PCB. This area should connect to the GND plane and have multiple via connections to the back of the PCB as well as connections to intermediate PCB layers. The GND plane area connecting to the exposed pad should be maximized to improve thermal performance.
- 5. Multi-layer PCB design is recommended.

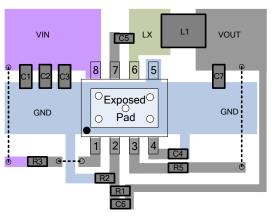


Figure 22. Recommended PCB Layout Diagram for SP Package

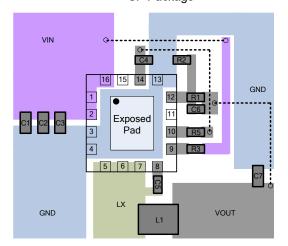
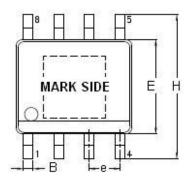


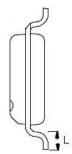
Figure 23. Recommended PCB Layout Diagram for W3 Package



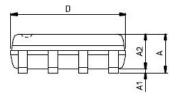
### **Outline Information**

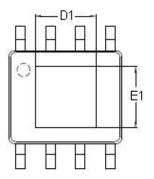
#### SOP-8L (Exposed Pad) Package (Unit: mm)





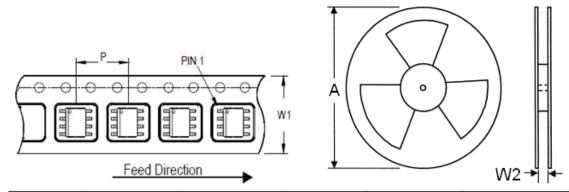
П	SYMBOLS	DIMENSION I	N MILLIMETER
	UNIT	MIN	MAX
	Α	1.25	1.80
	A1	0.00	0.25
	A2	1.25	1.55
	В	0.31	0.51
	D	4.80	5.00
57	D1	2.80	3.50
<u> </u>	Е	3.80	4.00
	E1	2.05	2.56
	е	1.20	1.34
	Н	5.80	6.20
	L	0.40	1.27





Note 4: Followed from JEDEC MO-012-E.

### **Carrier Dimensions**

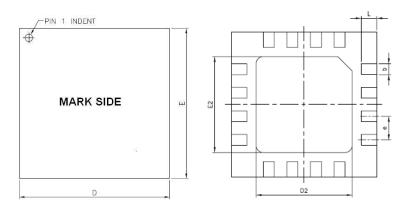


Tape Size	Pocket Pitch	Reel Size (A)		Reel Width	Empty Cavity	Units per Reel
(W1) mm	(P) mm	in	mm	(W2) mm	Length mm	
12	8	13	330	12.4	400~1000	2,500



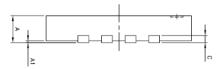
### **Outline Information (Continued)**

TQFN-16L (3mm×3mm) (pitch 0.5mm) Package (Unit: mm)

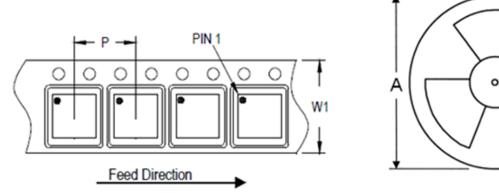


SYMBOLS	DIMENSION IN MILLIMETER							
UNIT	MIN	MAX						
Α	0.70	0.80						
A1	0.00	0.05						
С	0.19	0.30						
E	2.90	3.10						
D	2.90	3.10						
L	0.25	0.50						
b	0.18	0.30						
е	0.45	0.55						
E2	1.50	1.80						
D2	1.50	1.80						
N. 4 - E. E. II.	ILCO ILCO M	Note 5: Followed from JEDEC MO 220						

Note 5: Followed from JEDEC MO-220.



### **Carrier Dimensions**



Tape Size	Pocket Pitch	Reel Size (A)		Reel Width	Empty Cavity	Units per Reel
(W1) mm	(P) mm	in	mm	(W2) mm	Length mm	
12	8	13	330	12.4	400~1000	3,000